

Abstract

The present invention discloses an active-hydrogen-containing curing agent having a phosphorus group, and a flame retardant cured epoxy resin which can be prepared via an addition reaction between the active hydrogen and the epoxide group of an epoxy resin. The cured flame retardant epoxy resin is environmentally friendly and is suitable for printed circuit board and semiconductor encapsulation applications. The phosphorus group of the curing agent has a chemical structure as follows:

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or

wherein Ar is a substituted or un-

substituted phenyl or phenoxy.